



Semiconductor Industry Technologists to Debate 45nm Patterning Issues at Applied Materials' Forum During IITC

June 2, 2006

SANTA CLARA, Calif.--(BUSINESS WIRE)--June 2, 2006--Applied Materials, Inc. will host a technical forum on Monday, June 5, in Burlingame, Calif., in conjunction with the prestigious International Interconnect Technology Conference (IITC). A panel of prominent industry leaders and experts will discuss critical interconnect patterning issues facing chipmakers as demand for more advanced devices pushes the limits of IC lithographic patterning capabilities.

While new imaging technologies that overcome the resolution limitations of conventional exposure tools are being developed, efforts are also underway to extend existing lithography capabilities through an array of critical patterning and post-print applications. The forum's panel will share their views on what techniques and innovations can best meet current and future interconnect patterning requirements.

Panel: Moderated by Dr. Krishna Saraswat, Stanford University

- Christophe Verove, Crolles2 Alliance
- Jeff Gambino, IBM Corporation
- Rudi Cartuyvels, IMEC
- Douglas Yu, TSMC
- Jim Ryan, Albany Nanotech
- Farhad Moghadam, Applied Materials

When/Where:

- Monday, June 5, 2006
- Hyatt Regency Hotel, 1333 Bayshore Highway, Burlingame
- 5:00pm Registration and reception
- 6:00pm Panel discussion and Q&A

To Register: http://www.appliedmaterials.com/2006_IITC/

Applied Materials, Inc. (Nasdaq:AMAT) is the global leader in nanomanufacturing technology(TM) solutions for the electronics industry with a broad portfolio of innovative equipment, service and software products. At Applied Materials, we apply nanomanufacturing technology to improve the way people live. Learn more at www.appliedmaterials.com.

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